



# FGB20N60SFD\_F085

## 600V, 20A Field Stop IGBT

### Features

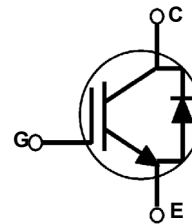
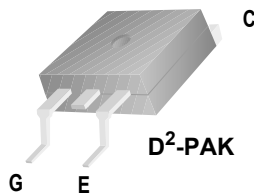
- High current capability
- Low saturation voltage:  $V_{CE(sat)} = 2.2V @ I_C = 20A$
- High input impedance
- Fast switching
- Qualified to Automotive Requirements of AEC-Q101
- RoHS compliant

### General Description

Using novel field-stop IGBT technology, Fairchild's new series of field-stop IGBTs offers the optimum performance for automotive chargers, inverters, and other applications where low conduction and switching losses are essential.

### Applications

- Inverters, SMPS, PFC, UPS
- Automotive Chargers, Converters, High Voltage Auxiliaries



### Absolute Maximum Ratings

Symbol	Description	Ratings	Units
$V_{CES}$	Collector to Emitter Voltage	600	V
$V_{GES}$	Gate to Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C = 25^\circ C$	40	A
	Collector Current @ $T_C = 100^\circ C$	20	A
$I_{CM(1)}$	Pulsed Collector Current @ $T_C = 25^\circ C$	60	A
$I_F$	Diode Forward Current @ $T_C = 25^\circ C$	20	A
	Diode Forward Current @ $T_C = 100^\circ C$	10	A
$I_{FM(1)}$	Pulsed Diode Maximum Forward Current	60	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ C$	208	W
	Maximum Power Dissipation @ $T_C = 100^\circ C$	83	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ C$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ C$
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Ratings	Units
$R_{\theta JC}(IGBT)(2)$	Thermal Resistance, Junction to Case	0.6	$^\circ C/W$
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	2.6	$^\circ C/W$

Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (PCB Mount)(2)	75	$^\circ C/W$

## Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Type	Qty per Tube	Max Qty per Box
FGB20N60SFD	FGB20N60SFD_F085	TO-263	Tube	50ea	-

## Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{CES}$	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	600	-	-	V
$\frac{\Delta V_{CES}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	-	0.79	-	V/°C
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	$\mu A$
		ICES at 80%*BV <sub>CES</sub> , 150°C	-	-	250	
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
<b>On Characteristics</b>						
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 250\mu A, V_{CE} = V_{GE}$	4.0	4.8	6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 20A, V_{GE} = 15V$	-	2.2	2.85	V
		$I_C = 20A, V_{GE} = 15V, T_C = 125^\circ C$	-	2.4	-	V
<b>Dynamic Characteristics</b>						
$C_{ies}$	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V, f = 1MHz$	-	940	1250	pF
$C_{oes}$	Output Capacitance		-	110	146	pF
$C_{res}$	Reverse Transfer Capacitance		-	40	53	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 400V, I_C = 20A, R_G = 10\Omega, V_{GE} = 15V, \text{Inductive Load}, T_C = 25^\circ C$	-	10	13	ns
$t_r$	Rise Time		-	16	21	ns
$t_{d(off)}$	Turn-Off Delay Time		-	90	120	ns
$t_f$	Fall Time		-	24	36	ns
$E_{on}$	Turn-On Switching Loss		-	0.31	0.41	mJ
$E_{off}$	Turn-Off Switching Loss		-	0.13	0.21	mJ
$E_{ts}$	Total Switching Loss		-	0.44	0.59	mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 400V, I_C = 20A, R_G = 10\Omega, V_{GE} = 15V, \text{Inductive Load}, T_C = 125^\circ C$	-	12	16	ns
$t_r$	Rise Time		-	16	21	ns
$t_{d(off)}$	Turn-Off Delay Time		-	95	126	ns
$t_f$	Fall Time		-	28	43	ns
$E_{on}$	Turn-On Switching Loss		-	0.45	0.60	mJ
$E_{off}$	Turn-Off Switching Loss		-	0.21	0.38	mJ
$E_{ts}$	Total Switching Loss		-	0.66	0.88	mJ
$Q_g$	Total Gate Charge	$V_{CE} = 400V, I_C = 20A, V_{GE} = 15V$	-	63	95	nC
$Q_{ge}$	Gate to Emitter Charge		-	7	11	nC
$Q_{gc}$	Gate to Collector Charge		-	32	48	nC

**Electrical Characteristics of the Diode**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Units	
$V_{FM}$	Diode Forward Voltage	$I_F = 10\text{A}$	$T_C = 25^\circ\text{C}$	-	1.9	2.5	V
			$T_C = 125^\circ\text{C}$	-	1.7	-	
$t_{rr}$	Diode Reverse Recovery Time	$I_{ES} = 10\text{A}, dI_{ES}/dt = 200\text{A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	-	111	-	ns
			$T_C = 125^\circ\text{C}$	-	204	-	
$Q_{rr}$	Diode Reverse Recovery Charge	$I_{ES} = 10\text{A}, dI_{ES}/dt = 200\text{A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	-	174	244	nC
			$T_C = 125^\circ\text{C}$	-	463	-	

**Notes:**

1: Repetitive rating: Pulse width limited by max. junction temperature

2:  $R_{thjc}$  for D2-PAK: according to Mil standard 883-1012 test method.

$R_{thja}$  for D2-PAK: according to JESD51-2, test method environmental condition and JESD51-3, low effective thermal conductivity test board for leaded surface mount package. thermal measurements. JESD51-2: Integrated Circuits Thermal Test Method Environmental Conditions - Natural Convection (Still Air).

## Typical Performance Characteristics

Figure 1. Typical Output Characteristics

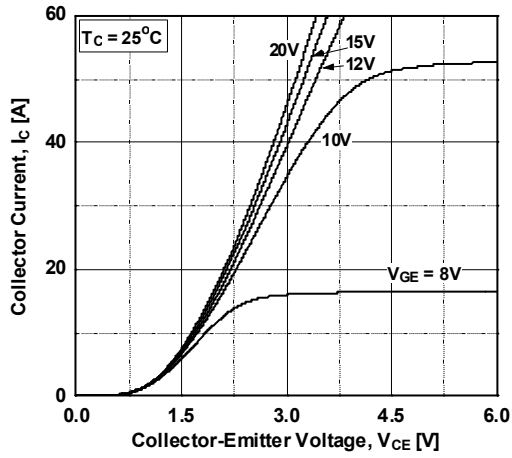


Figure 2. Typical Output Characteristics

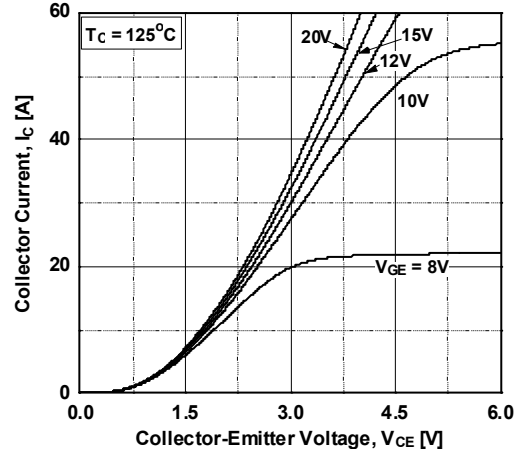


Figure 3. Typical Saturation Voltage Characteristics

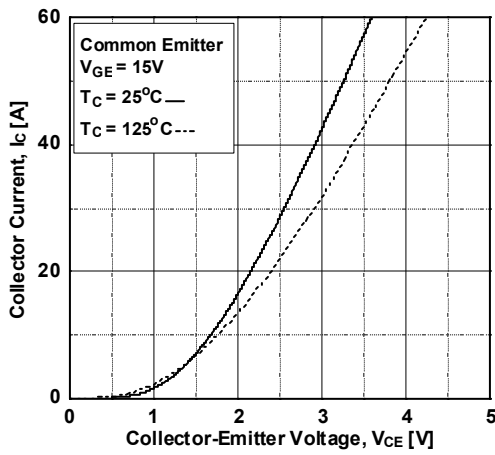


Figure 4. Transfer Characteristics

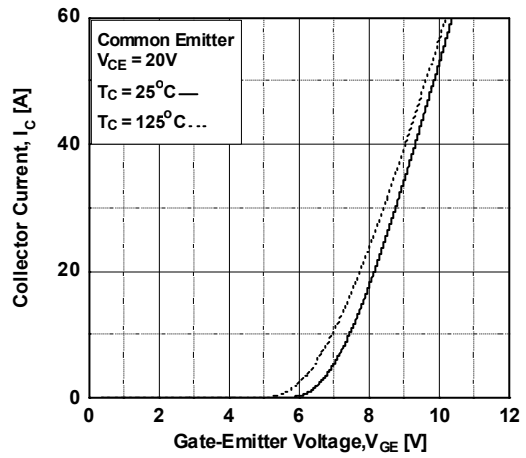


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

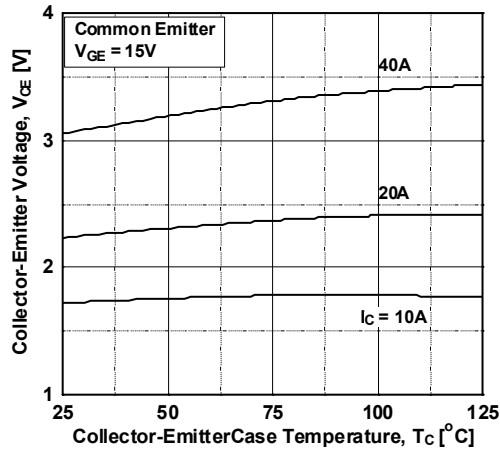
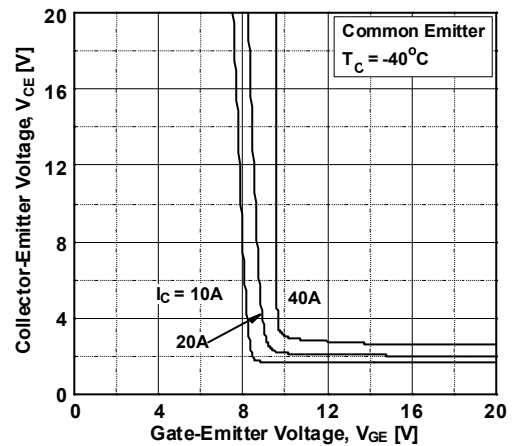


Figure 6. Saturation Voltage vs. Vge



## Typical Performance Characteristics

Figure 7. Saturation Voltage vs.  $V_{GE}$

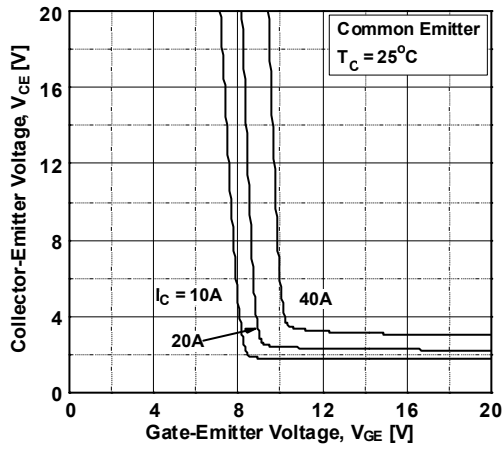


Figure 8. Saturation Voltage vs.  $V_{GE}$

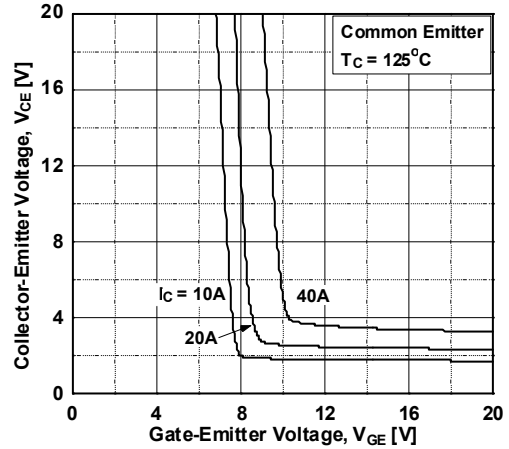


Figure 9. Capacitance Characteristics

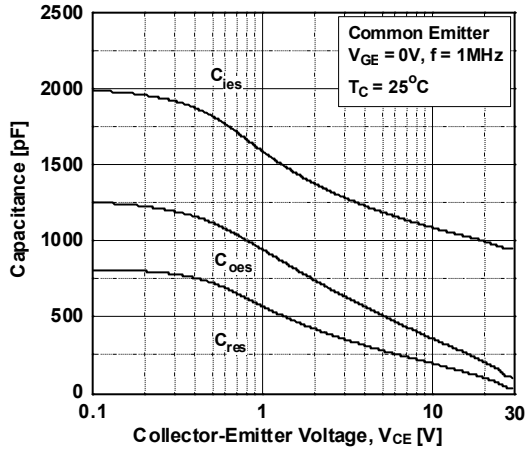


Figure 10. Gate charge Characteristics

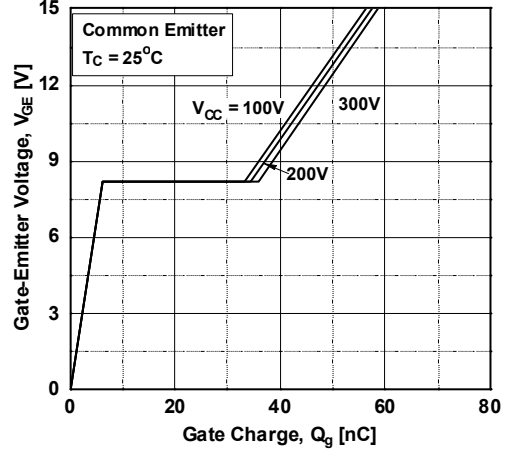


Figure 11. SOA Characteristics

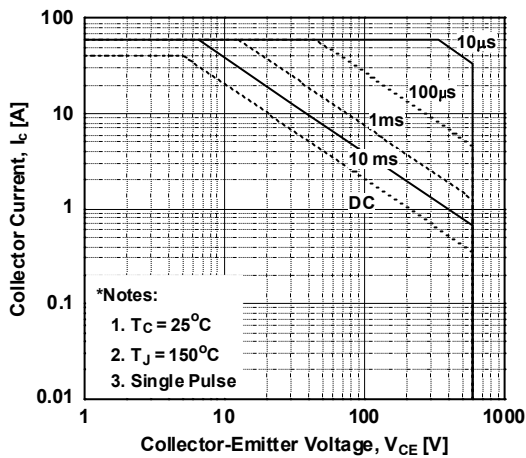
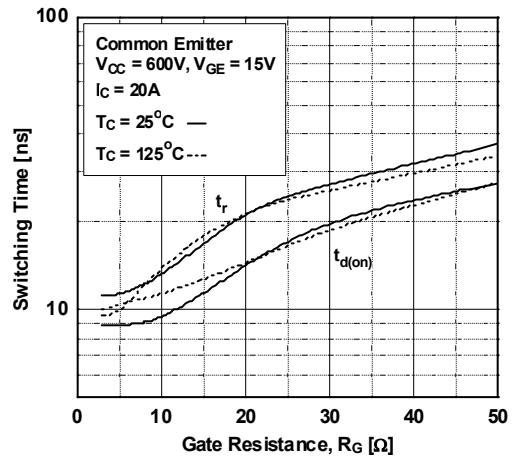


Figure 12. Turn-on Characteristics vs. Gate Resistance



## Typical Performance Characteristics

Figure 13. Turn-off Characteristics vs. Gate Resistance

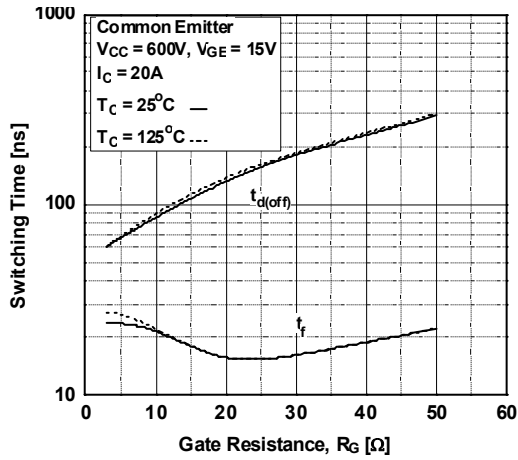


Figure 14. Turn-on Characteristics vs. Collector Current

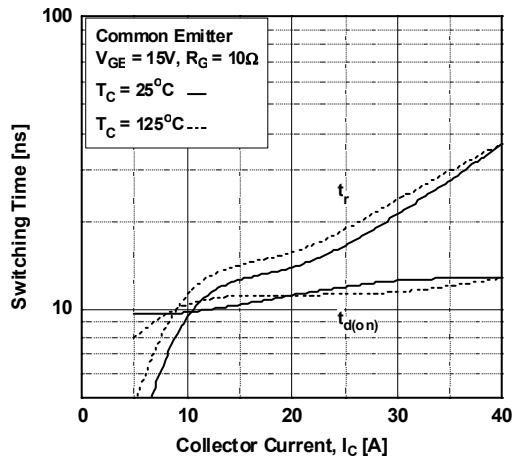


Figure 15. Turn-off Characteristics vs. Collector Current

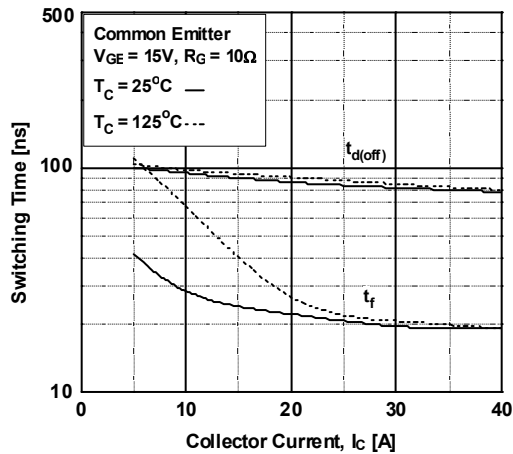


Figure 16. Switching Loss vs. Gate Resistance

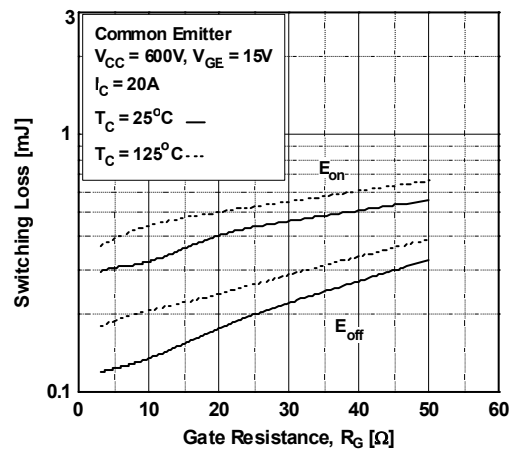


Figure 17. Switching Loss vs. Collector Current

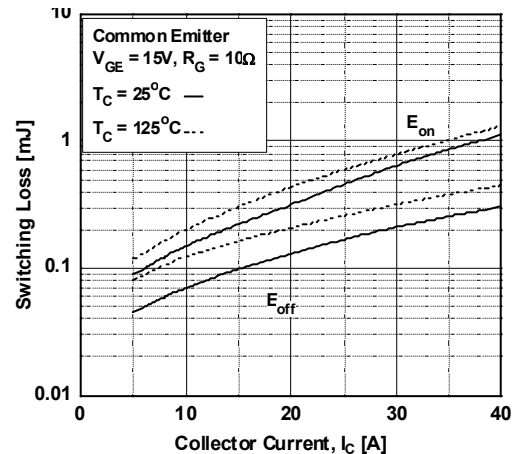
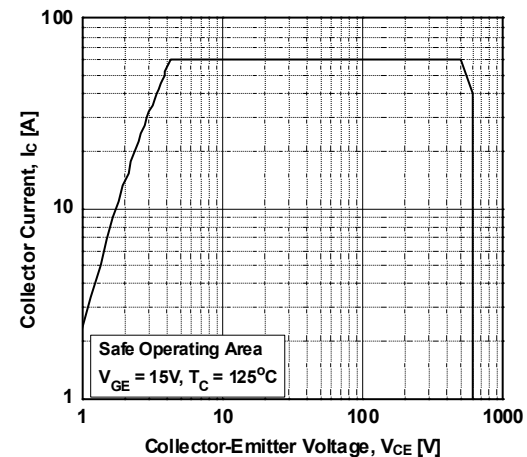


Figure 18. Turn off Switching SOA Characteristics



## Typical Performance Characteristics

Figure 19. Forward Characteristics

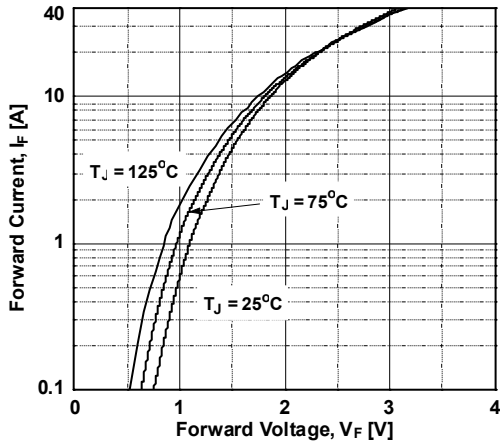


Figure 20. Typical Reverse Current vs. Reverse Voltage

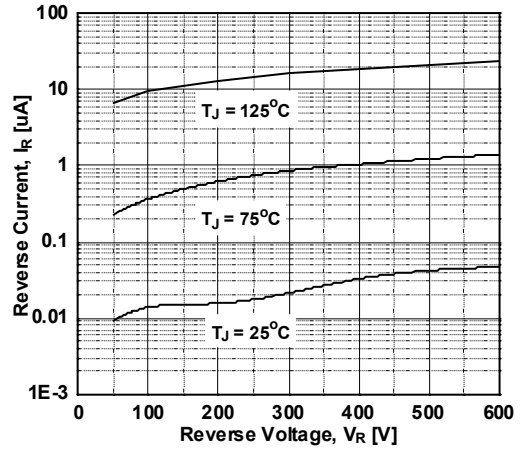


Figure 21. Stored Charge

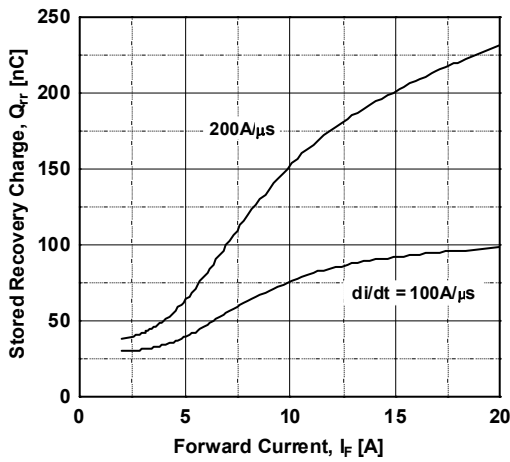


Figure 22. Reverse Recovery Time

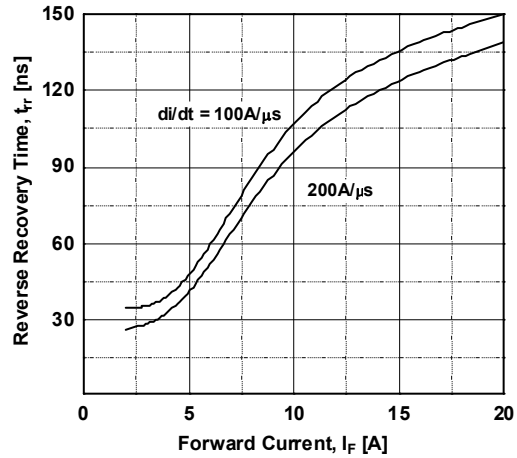
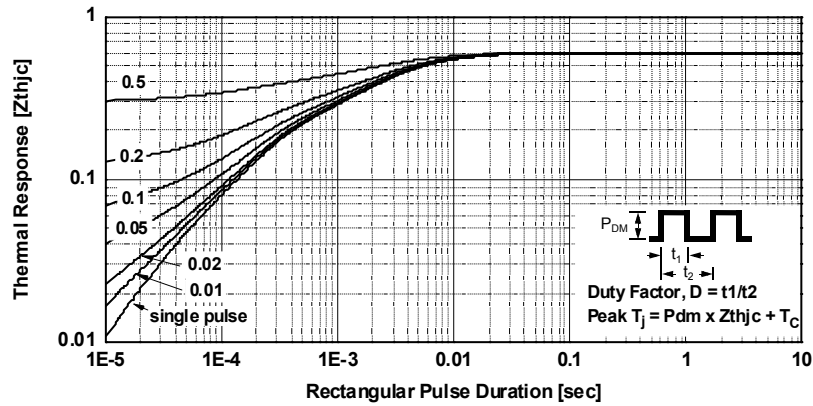
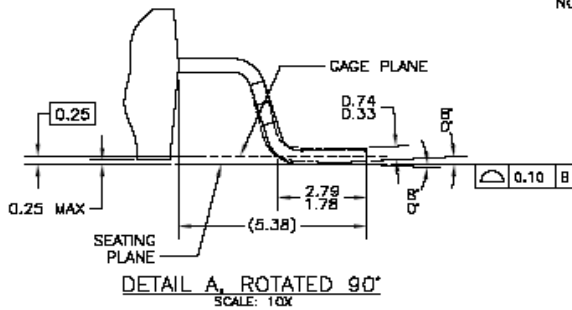
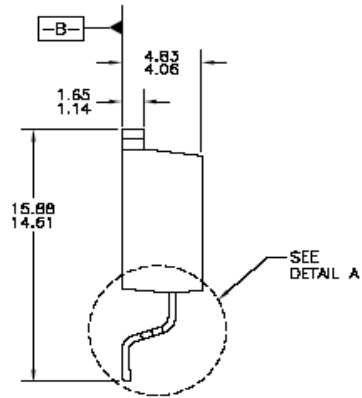
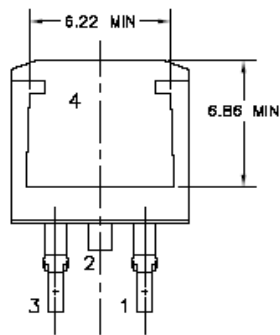
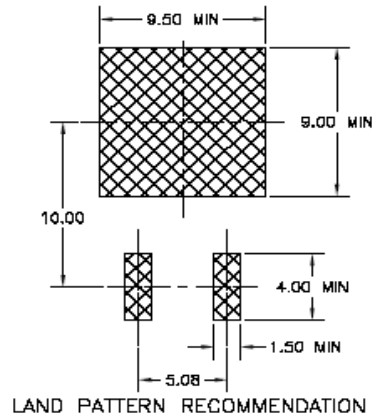
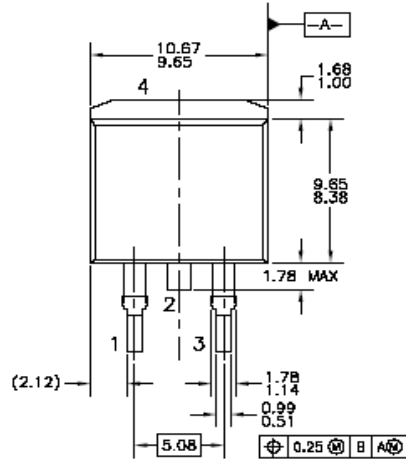


Figure 23. Transient Thermal Impedance of IGBT



# Mechanical Dimensions

## D<sup>2</sup>PAK



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) ALL DIMENSIONS ARE IN MILLIMETERS.
  - B) REFERENCE JEDEC, TO-263, ISSUE D, VARIATION AB, DATED JULY 2003.
  - C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1982.
  - D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
  - E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.

T02B3AD2REV D


Dimensions in Millimeters





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| AX-CAP®*  | FRFET®  | PowerXS™                              | <b>SYSTEM GENERAL</b> ®* |
| BitSiC™   | Global Power Resource <sup>SM</sup>             | Programmable Active Droop™            | TinyBoost®               |
| Build it Now™   | GreenBridge™                                    | QFET®                                 | TinyBuck®                |
| CorePLUS™   | Green FPS™                                      | QS™                                   | TinyCalc™                |
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| EfficientMax™   | MICROCOUPLER™                                   | SPM®                                  | TRUECURRENT®*            |
| ESBC™   | MicroFET™                                       | STEALTH™                              | μSerDes™                 |
|  | MicroPak™                                       | SuperFET®                             | UHC®                     |
| Fairchild®  | MicroPak2™                                      | SuperSOT™-3                           | Ultra FRFET™             |
| Fairchild Semiconductor®  | MillerDrive™                                    | SuperSOT™-6                           | UniFET™                  |
| FACT Quiet Series™  | MotionMax™                                      | SuperSOT™-8                           | VCX™                     |
| FACT®   | mWSaver®  | SupreMOS®                             | VisualMax™               |
| FAST®   | OptoHiT™  | SyncFET™                              | VoltagePlus™             |
| FastvCore™  | OPTOLOGIC®                                      |                                       | XS™                      |
| FETBench™   | OPTOPLANAR®                                     |                                       |                          |
| FPS™  |   |                                       |                          |

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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.



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